



GROUP 1700

MAY 10 2003

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No*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. HIROSE, et al
Serial No.: 09/800,495
Filed: March 8, 2001
For: METHOD OF DETECTING AND MEASURING ENDPOINT OF
POLISHING PROCESSING AND ITS APPARATUS AND
METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE
USING THE SAME
Group: 1765
Examiner: L. Umez Eronini

AMENDMENT

Mail Stop Fee-Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 15, 2003

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated January 15, 2003.

IN THE CLAIMS:

Please amend claims 1, 2, 9 and 10 as follows:

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1. (twice amended) A method of detecting an endpoint of polishing processing, comprising the steps of:
- simultaneously irradiating onto a film formed on a surface of a wafer under
- polishing processing lights having different wavelengths from one another;
- detecting reflected lights of different wavelengths from said film caused by the irradiation with the lights of the different wavelengths; and